

#2 PA Amdt. A
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R. J. Lee

PATENT
Attorney Docket No. SAM-0201

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jong-hyon Ahn
Filing Date: Herewith
Title: METAL INTERCONNECT LAYER OF SEMICONDUCTOR DEVICE
AND METHOD FOR FORMING A METAL INTERCONNECT LAYER

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.10

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June 12, 2001
Date

Vanessa Marakas
Vanessa Marakas

BOX PATENT APPLICATION
Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to prosecution on the merits, please amend the above-identified application as follows:

In the Claims

Please amend the claims as follows:

10. (Amended) A metal interconnect layer for a semiconductor device,
comprising:
a first upper portion having a first width;
a second middle portion having a second width, the second width being wider
than the first width; and
a third lower portion having a third width, the third width being narrower than the
second width.